

N-channel 1050 V, 0.110 Ω typ., 46 A MDmesh™ DK5 Power MOSFET in an ISOTOP package

Datasheet - production data

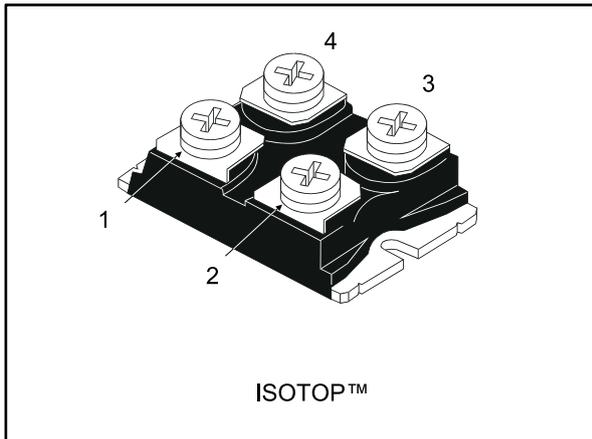
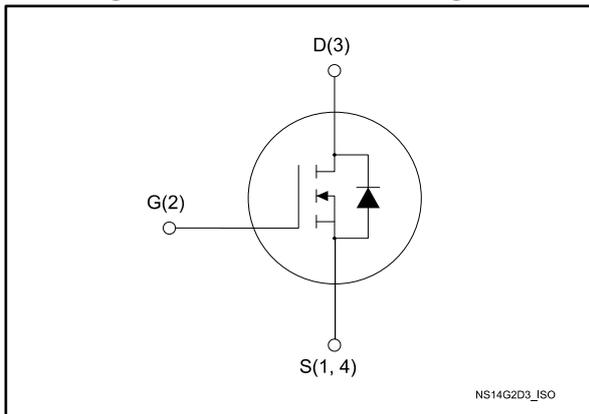


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STE60N105DK5	1050 V	0.120 Ω	46 A	680 W

- Fast-recovery body diode
- Best R_{DS(on)} x area
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness

Applications

- Switching applications

Description

This very high voltage N-channel Power MOSFET is part of the MDmesh™ DK5 fast recovery diode series. The MDmesh™ DK5 combines very low recovery charge (Q_{rr}) and recovery time (t_{rr}) with an excellent improvement in R_{DS(on)} * area and one of the most effective switching behaviors, ideal for half bridge and full bridge converters.

Table 1: Device summary

Order code	Marking	Packages	Packaging
STE60N105DK5	60N105DK5	ISOTOP	Tube

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Prerelease product(s)



1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	46	A
	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	30	A
$I_{DM}^{(1)}$	Drain current (pulsed)	184	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	680	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	V/ns
V_{ISO}	Insulation withstand voltage (AC-RMS)	2.5	kV
T_j	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature range		

Notes:

(1) Pulse width limited by safe operating area

(2) $I_{SD} \leq 23\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$; $V_{DS\text{ peak}} \leq V_{(BR)DSS}$, $V_{DD} = 525\text{ V}$

(3) $V_{DS} \leq 840\text{ V}$

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.184	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	30	

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AS}	Single pulse avalanche energy (pulse width limited by T_{JMAX})	16	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$, $I_D = I_{AS}$, $V_{DD} = 50\text{ V}$)	1550	mJ

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 5: On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0 V	1050			V
I _{DSS}	Zero gate voltage drain current	V _{DS} = 1050 V, V _{GS} = 0 V			1	μA
		V _{DS} = 1050 V, V _{GS} = 0 V, T _C = 125 °C ⁽¹⁾			50	μA
I _{GSS}	Gate-body leakage current	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μA
V _{GS(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = 100 μA	3	4	5	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 23 A		0.110	0.120	Ω

Notes:

⁽¹⁾Defined by design, not subject to production test

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C _{iss}	Input capacitance	V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0 V	-	6675	-	pF
C _{oss}	Output capacitance		-	370	-	pF
C _{rss}	Reverse transfer capacitance		-	10	-	pF
C _{o(tr)} ⁽¹⁾	Equivalent capacitance time related	V _{GS} = 0 V, V _{DS} = 0 to 840 V	-	630	-	pF
C _{o(er)} ⁽²⁾	Equivalent capacitance energy related		-	219	-	
R _G	Intrinsic gate resistance	f = 1 MHz open drain	-	3	-	Ω
Q _g	Total gate charge	V _{DD} = 840 V, I _D = 46 A, V _{GS} = 10 V (see Figure 15: "Test circuit for gate charge behavior")	-	204	-	nC
Q _{gs}	Gate-source charge		-	36	-	nC
Q _{gd}	Gate-drain charge		-	133	-	nC

Notes:

⁽¹⁾Time related is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.

⁽²⁾Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.

Prerelease product(s)

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 525 \text{ V}$, $I_D = 23 \text{ A}$, $R_G = 4.7 \text{ } \Omega$, $V_{GS} = 10 \text{ V}$ (see Figure 14: "Test circuit for resistive load switching times" and Figure 19: "Switching time waveform")	-	40.6	-	ns
t_r	Rise time		-	64.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	262	-	ns
t_f	Fall time		-	49.5	-	ns

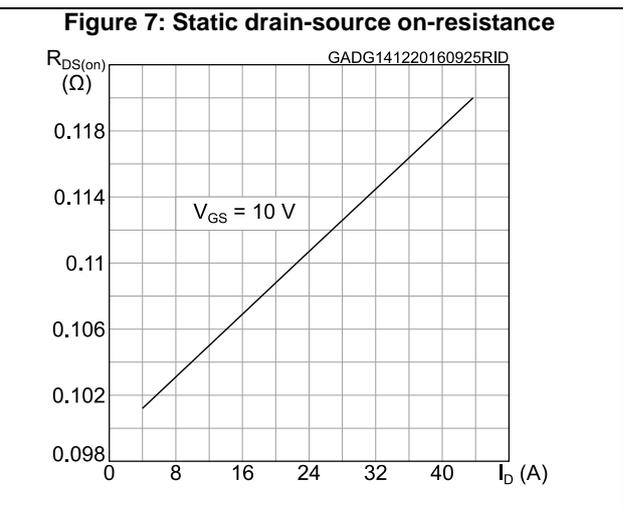
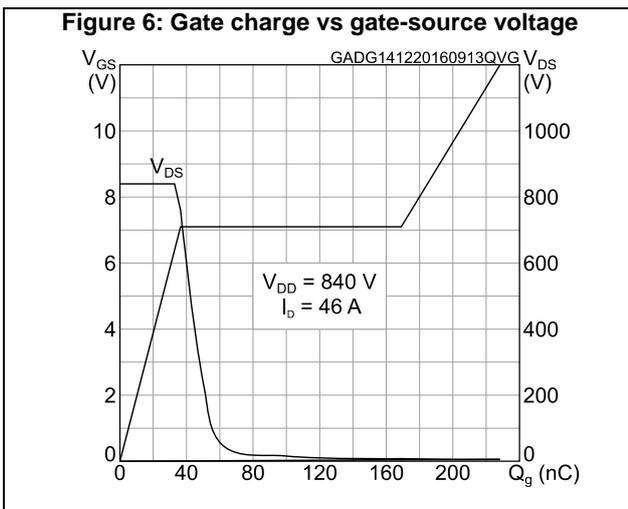
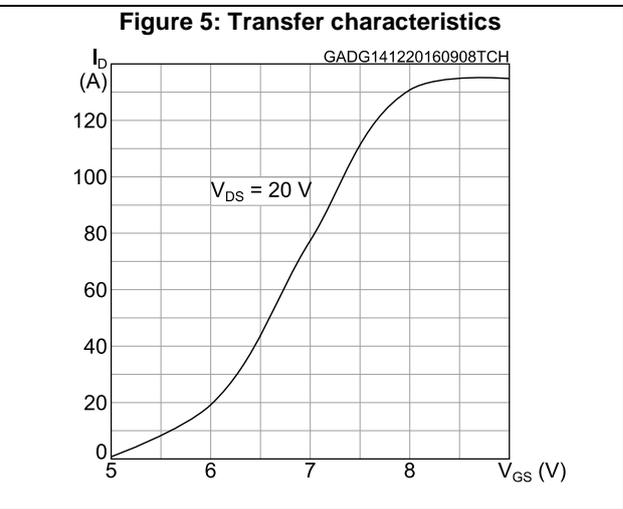
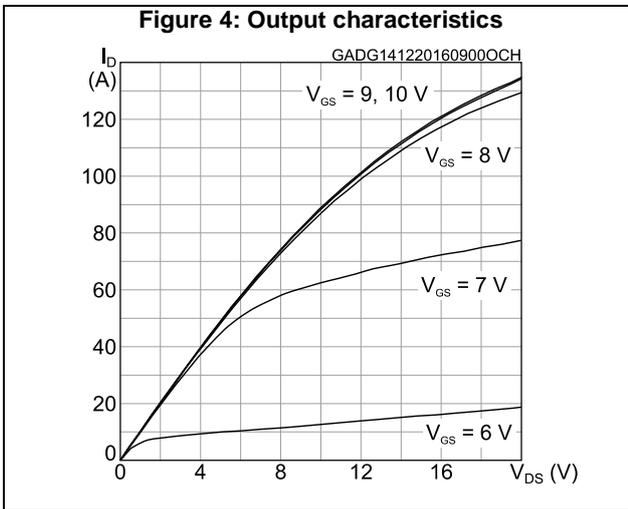
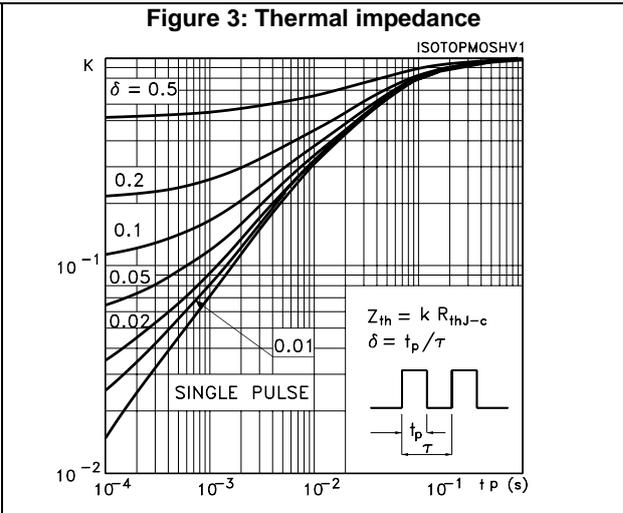
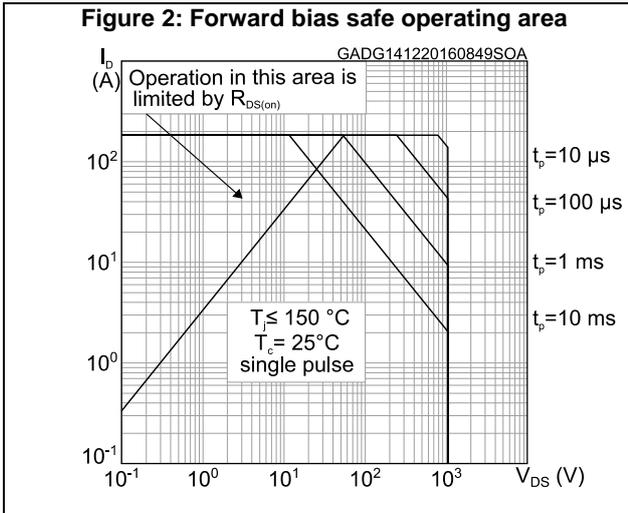
Table 8: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		46	A
I_{SDM}	Source-drain current (pulsed)		-		184	A
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 46 \text{ A}$, $V_{GS} = 0 \text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 46 \text{ A}$, $V_{DD} = 60 \text{ V}$, $di/dt = 100 \text{ A}/\mu\text{s}$ (see Figure 16: "Test circuit for inductive load switching and diode recovery times")	-	273		ns
Q_{rr}	Reverse recovery charge		-	3		μC
I_{RRM}	Reverse recovery current		-	23		A
t_{rr}	Reverse recovery time	$I_{SD} = 46 \text{ A}$, $V_{DD} = 60 \text{ V}$, $di/dt = 100 \text{ A}/\mu\text{s}$, $T_j = 150 \text{ } ^\circ\text{C}$ (see Figure 16: "Test circuit for inductive load switching and diode recovery times")	-	477		ns
Q_{rr}	Reverse recovery charge		-	10		μC
I_{RRM}	Reverse recovery current		-	42		A

Notes:

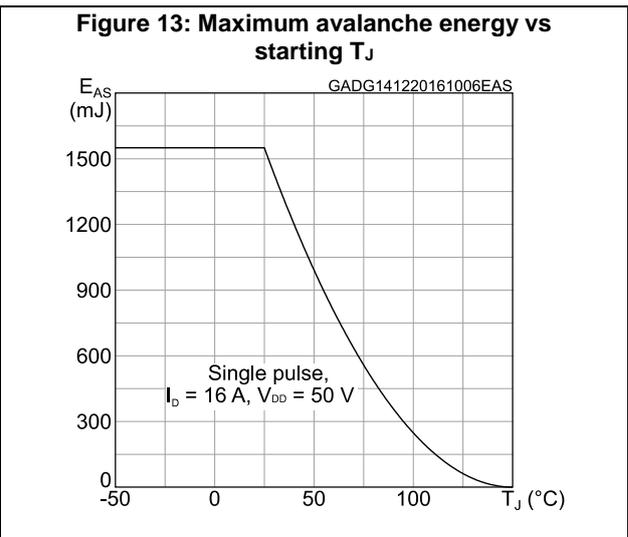
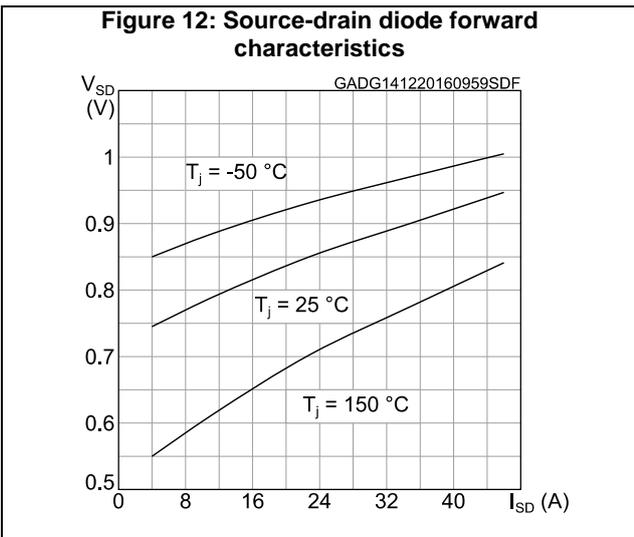
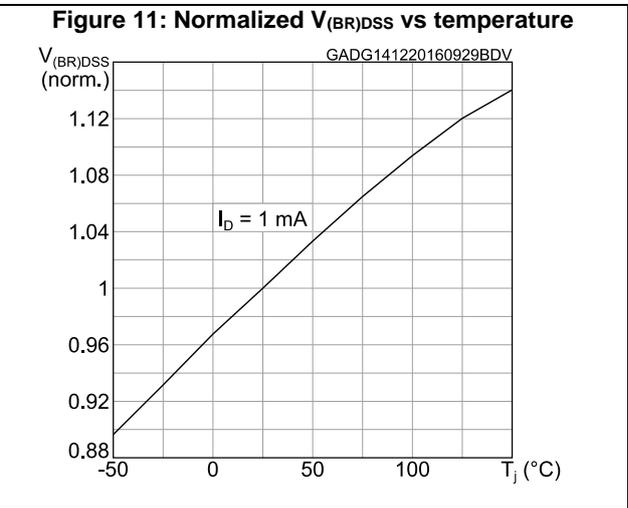
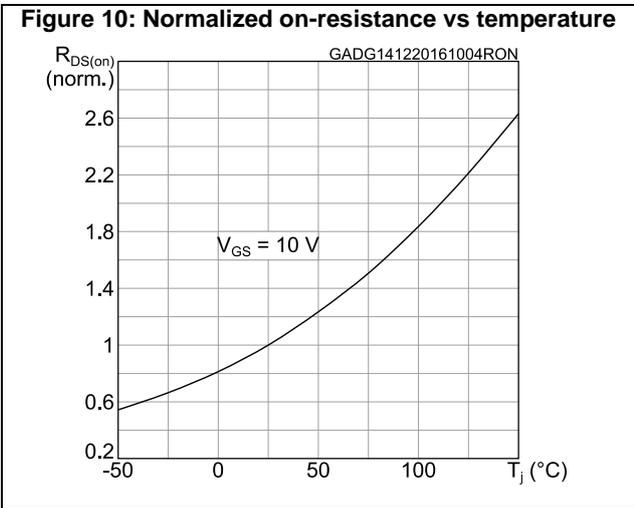
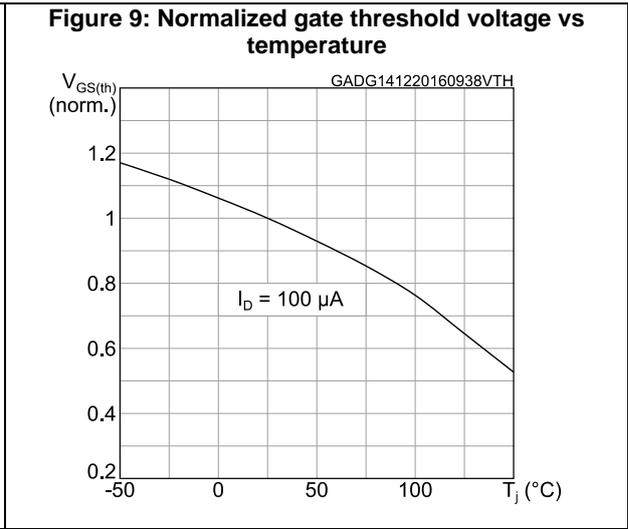
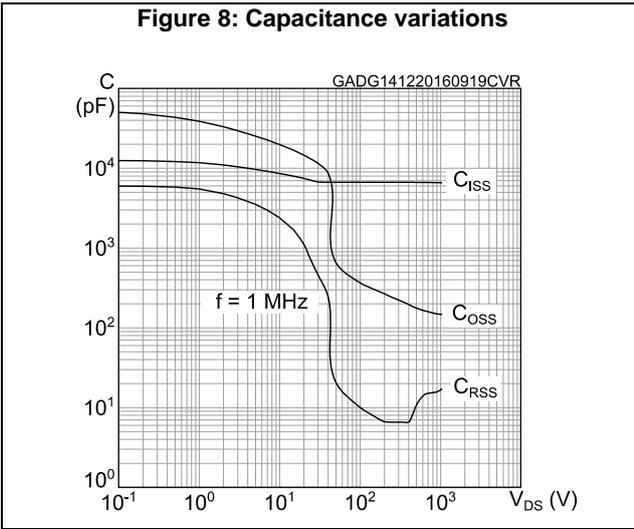
⁽¹⁾Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)



Prerelease product(s)

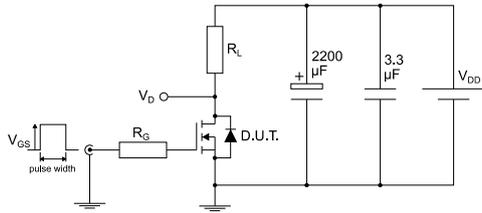




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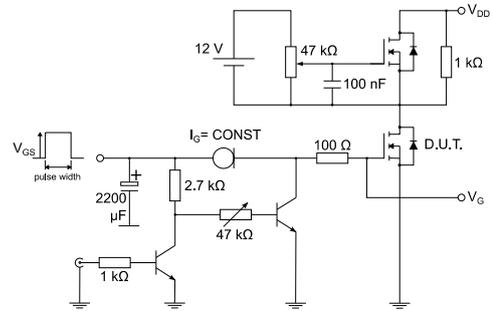
3 Test circuits

Figure 14: Test circuit for resistive load switching times



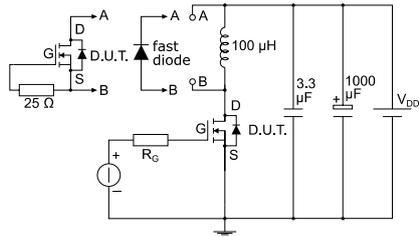
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Figure 15: Test circuit for gate charge behavior



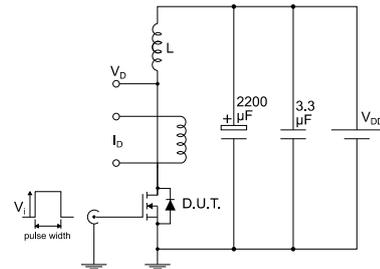
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Figure 16: Test circuit for inductive load switching and diode recovery times



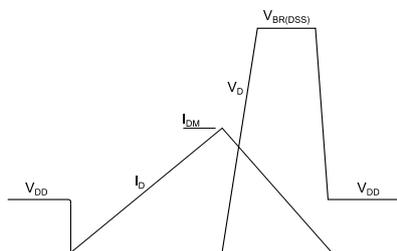
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Figure 17: Unclamped inductive load test circuit



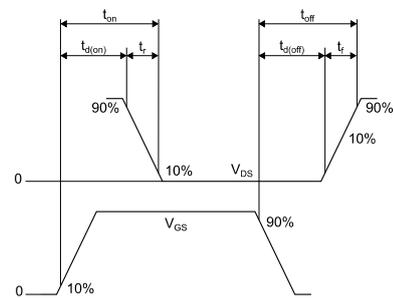
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Figure 18: Unclamped inductive waveform



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Figure 19: Switching time waveform



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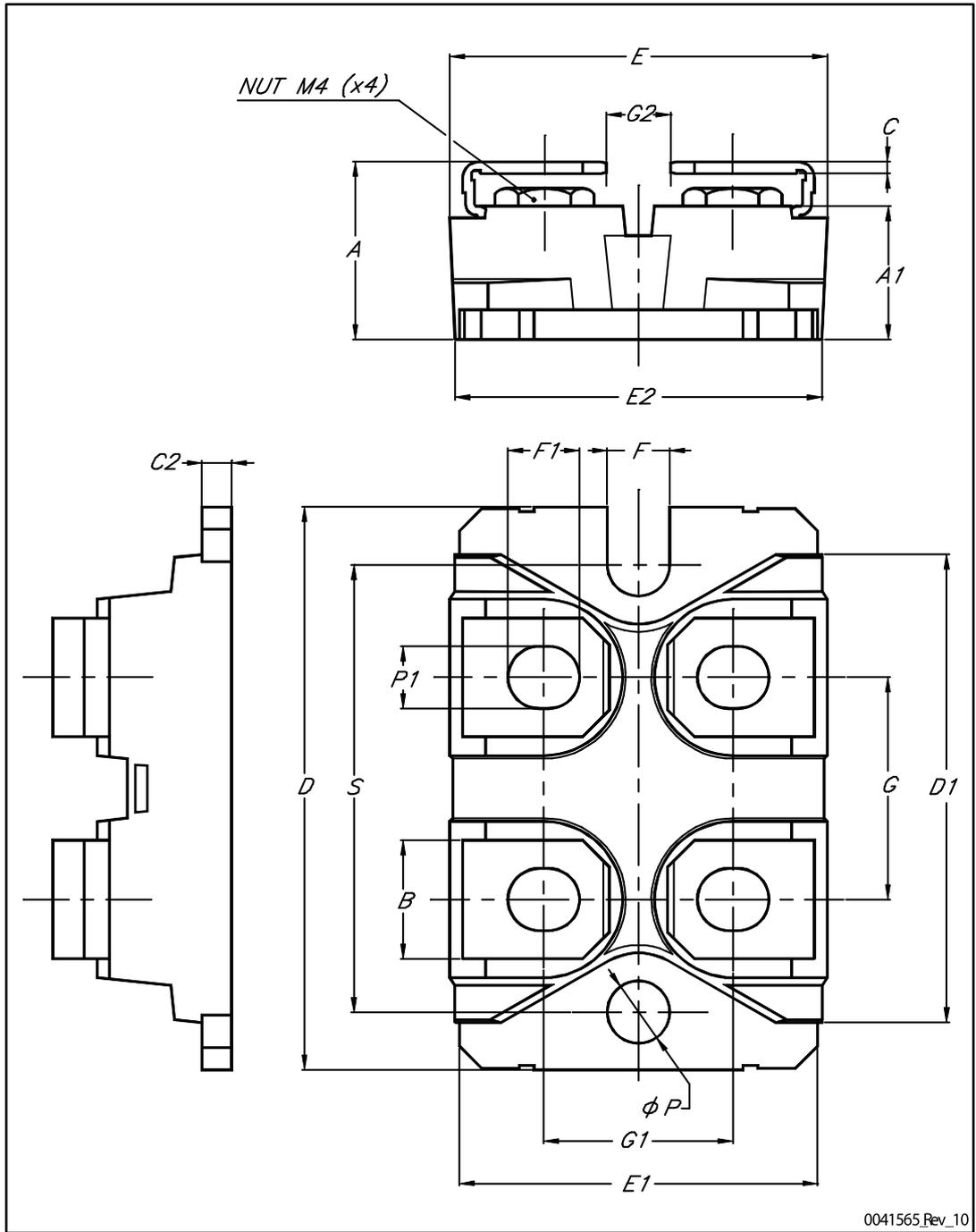
Prerelease product(s)

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 ISOTOP package information

Figure 20: ISOTOP outline



Prerelease product(s)

Table 9: ISOTOP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	11.80		12.20
A1	8.90		9.10
B	7.80		8.20
C	0.75		0.85
C2	1.95		2.05
D	37.80		38.20
D1	31.50		31.70
E	25.15		25.50
E1	23.85		24.15
E2		24.80	
G	14.90		15.10
G1	12.60		12.80
G2	3.50		4.30
F	4.10		4.30
F1	4.60		5
ØP	4		4.30
P1	4		4.40
S	30.10		30.30

5 Revision history

Table 10: Document revision history

Date	Revision	Changes
24-Jan-2013	1	First release
16-Dec-2016	2	Datasheet status promoted from preliminary to production data. Updated title, features, description and internal schematic diagram on cover page. Updated Section 1: "Electrical ratings" . Updated Section 2: "Electrical characteristics" . Added Section 2.1: "Electrical characteristics (curves)" . Minor text changes